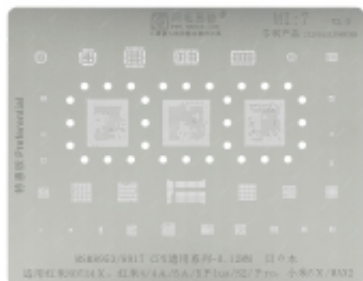


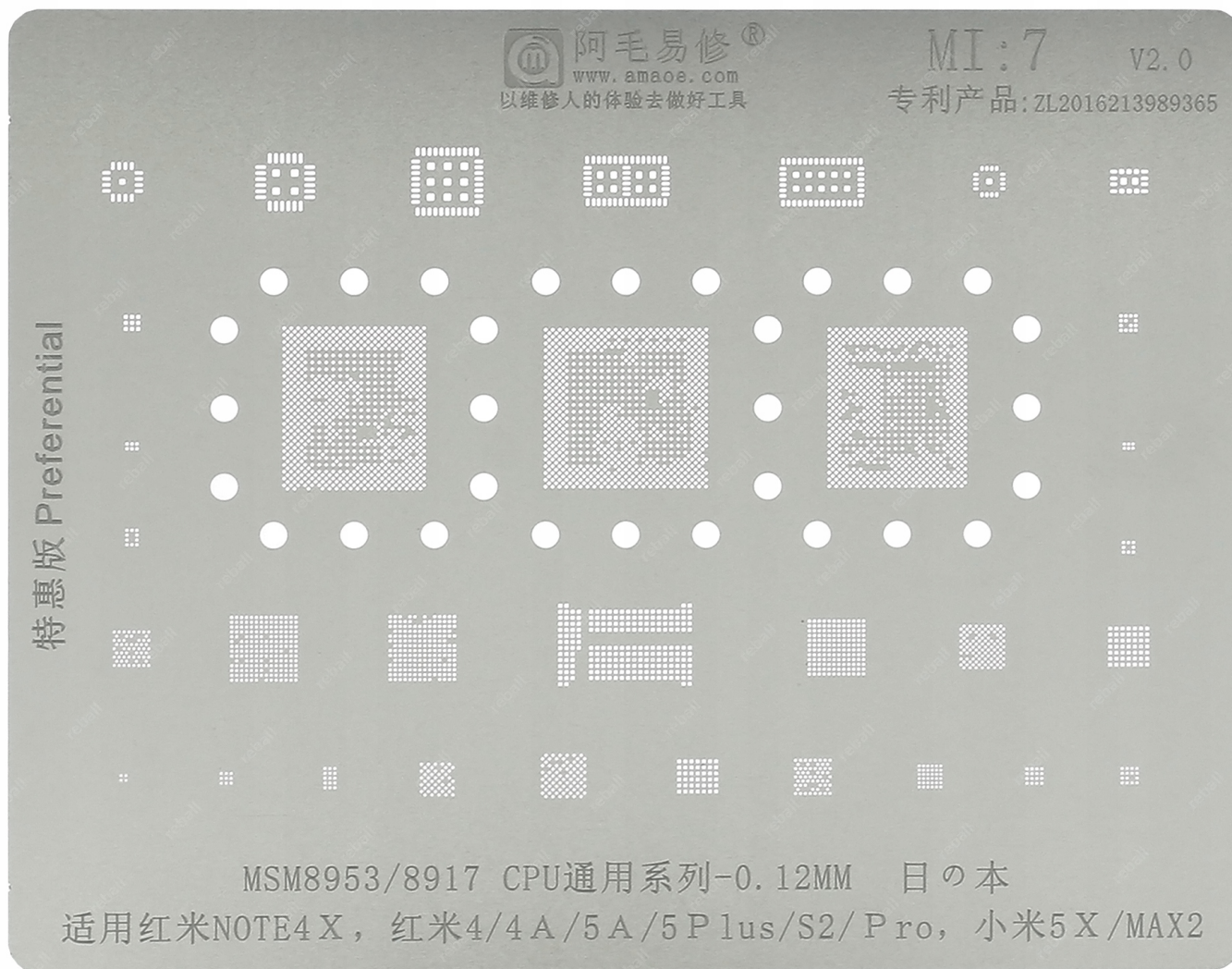
Link do produktu: <https://serwisowe.pl/sito-matryca-bgap-hotair-naprawa-smartfona-mi7-msm-8953-8917-xiaomi-redmi-p-5583.html>

SITO MATRYCA BGAP HOTAIR NAPRAWA SMARTFONA MI7 MSM 8953 8917 Xiaomi Redmi

Cena brutto	24,49 zł
Cena netto	19,91 zł
Dostępność	Aktualnie niedostępny
Czas wysyłki	24 godziny
Numer katalogowy	XGA00027
Kod EAN	6949639133694

Opis produktu

GA00027



SITO/MATRYCA BGA PLATE

AMAOE MI 7 V2.0

UWAGA:

Sito przeznaczone jest **do nakładania pasty lutowniczej!**

Maksymalna temp. dla sit przeznaczonych do bezpośredniego grzania to 280C.

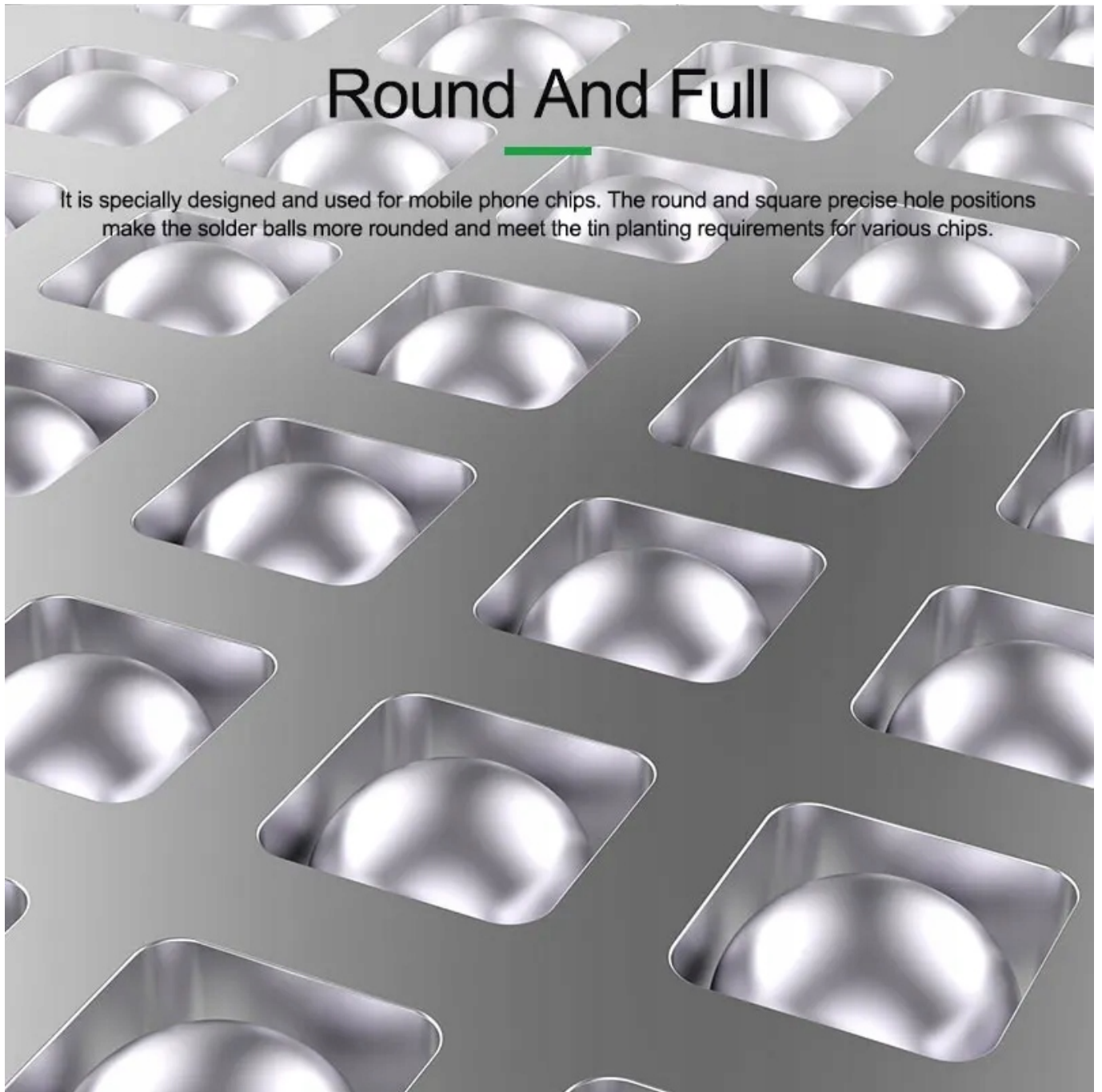
Parametry sita:

- sita: **MSM 8953 8917 Xiaomi 5X Max2 Redmi 4 4A 5A 5Plus S2 Pro**
- grubość: **0,12mm**
- waga netto: **5g**
- materiał: **stal**

Wszelkie reklamacje z tytułu przegrzania sita temperaturami wyższymi będą odrzucane!

Round And Full

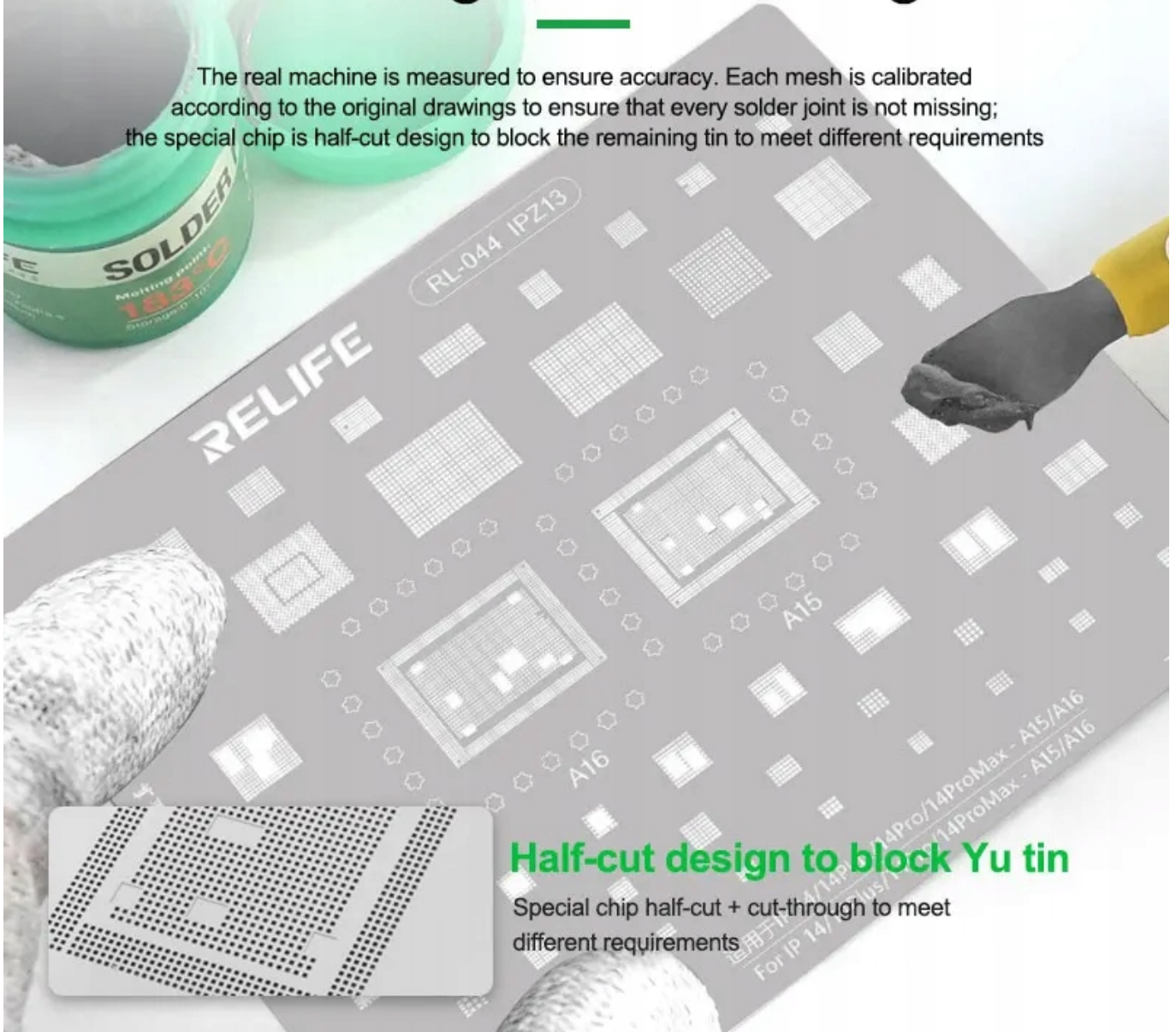
It is specially designed and used for mobile phone chips. The round and square precise hole positions make the solder balls more rounded and meet the tin planting requirements for various chips.





Half-cut Design, Precise Alignment

The real machine is measured to ensure accuracy. Each mesh is calibrated according to the original drawings to ensure that every solder joint is not missing; the special chip is half-cut design to block the remaining tin to meet different requirements



Half-cut design to block Yu tin

Special chip half-cut + cut-through to meet different requirements



01



High temperature and wear resistance

High-quality special steel is selected, which has good high temperature resistance and metal fatigue resistance, so that each tin point is heated evenly

Precision hole pitch design

The round and square precise hole position makes the solder balls more rounded and prevents the mesh holes from jamming the solder balls

02

